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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	18
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 17x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	20-DIP (0.300", 7.62mm)
Supplier Device Package	20-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f15345-e-p

6.0 DEVICE INFORMATION AREA

The Device Information Area (DIA) is a dedicated region in the program memory space; it is a new feature in the PIC16(L)F15325/45 family of devices. The DIA contains the calibration data for the internal temperature indicator module, stores the Microchip Unique Identifier words and the Fixed Voltage Reference voltage readings measured in mV.

The complete DIA table is shown in Table 6-1: Device Information Area, followed by a description of each region and its functionality. The data is mapped from 8100h to 811Fh in the PIC16(L)F15325/45 family. These locations are read-only and cannot be erased or modified. The data is programmed into the device during manufacturing.

TABLE 6-1: DEVICE INFORMATION AREA

Address Range	Name of Region	Standard Device Information
8100h-8108h	MUI0	Microchip Unique Identifier (9 Words)
	MUI1	
	MUI2	
	MUI3	
	MUI4	
	MUI5	
	MUI6	
	MUI7	
	MUI8	
8109h	MUI9	1 Word Reserved
810Ah-8111h	EUI0	Unassigned (8 Words)
	EUI1	
	EUI2	
	EUI3	
	EUI4	
	EUI5	
	EUI6	
	EUI7	
8112h	TSLR1	Unassigned (1 word)
8113h	TSLR2	Temperature indicator ADC reading at 90°C (low range setting)
8114h	TSLR3	Unassigned (1 word)
8115h	TSHR1	Unassigned (1 word)
8116h	TSHR2	Temperature indicator ADC reading at 90°C (high range setting)
8117h	TSHR3	Unassigned (1 Word)
8118h	FVRA1X	ADC FVR1 Output voltage for 1x setting (in mV)
8119h	FVRA2X	ADC FVR1 Output Voltage for 2x setting (in mV)
811Ah	FVRA4X(1)	ADC FVR1 Output Voltage for 4x setting (in mV)
811Bh	FVRC1X	Comparator FVR2 output voltage for 1x setting (in mV)
811Ch	FVRC2X	Comparator FVR2 output voltage for 2x setting (in mV)
811Dh	FVRC4X(1)	Comparator FVR2 output voltage for 4x setting (in mV)
811Eh-811Fh		Unassigned (1 Word)

Note 1: Value not present on LF devices.

9.2.1.4 4x PLL

The oscillator module contains a PLL that can be used with external clock sources and internal oscillator to provide a system clock source. The input frequency for the PLL must fall within specifications. See the PLL Clock Timing Specifications in Table 37-9.

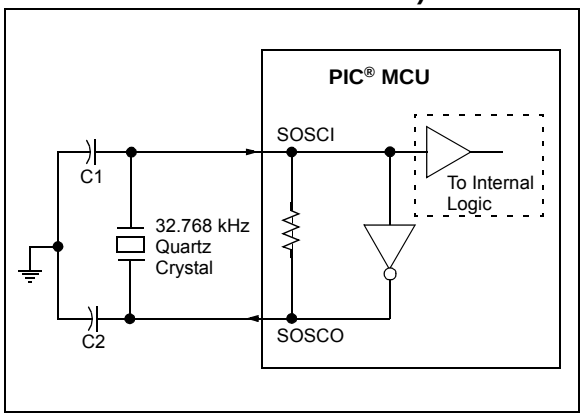
The PLL may be enabled for use by one of two methods:

1. Program the RSTOSC bits in the Configuration Word 1 to enable the EXTOSC with 4x PLL.
2. Write the NOSC bits in the OSCCON1 register to enable the EXTOSC with 4x PLL.

9.2.1.5 Secondary Oscillator

The secondary oscillator is a separate oscillator block that can be used as an alternate system clock source. The secondary oscillator is optimized for 32.768 kHz, and can be used with an external crystal oscillator connected to the SOSCI and SOSCO device pins, or an external clock source connected to the SOSCIN pin. Refer to **Section 9.3 "Clock Switching"** for more information.

FIGURE 9-5: QUARTZ CRYSTAL OPERATION (SECONDARY OSCILLATOR)



Note 1: Quartz crystal characteristics vary according to type, package and manufacturer. The user should consult the manufacturer data sheets for specifications and recommended application.

2: Always verify oscillator performance over the V_{DD} and temperature range that is expected for the application.

3: For oscillator design assistance, reference the following Microchip Application Notes:

- AN826, "*Crystal Oscillator Basics and Crystal Selection for rfPIC® and PIC® Devices*" (DS00826)
- AN849, "*Basic PIC® Oscillator Design*" (DS00849)
- AN943, "*Practical PIC® Oscillator Analysis and Design*" (DS00943)
- AN949, "*Making Your Oscillator Work*" (DS00949)
- TB097, "*Interfacing a Micro Crystal MS1V-T1K 32.768 kHz Tuning Fork Crystal to a PIC16F690/SS*" (DS91097)
- AN1288, "*Design Practices for Low-Power External Oscillators*" (DS01288)

10.6 Register Definitions: Interrupt Control

REGISTER 10-1: INTCON: INTERRUPT CONTROL REGISTER

R/W-0/0	R/W-0/0	U-0	U-0	U-0	U-0	U-0	R/W-1/1
GIE	PEIE	—	—	—	—	—	INTEDG
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **GIE:** Global Interrupt Enable bit
1 = Enables all active interrupts
0 = Disables all interrupts

bit 6 **PEIE:** Peripheral Interrupt Enable bit
1 = Enables all active peripheral interrupts
0 = Disables all peripheral interrupts

bit 5-1 **Unimplemented:** Read as ‘0’

bit 0 **INTEDG:** Interrupt Edge Select bit
1 = Interrupt on rising edge of INT pin
0 = Interrupt on falling edge of INT pin

Note: Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the Global Enable bit, GIE, of the INTCON register. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

REGISTER 10-3: PIE1: PERIPHERAL INTERRUPT ENABLE REGISTER 1

R/W-0/0	R/W-0/0	U-0	U-0	U-0	U-0	R/W-0/0	R/W-0/0
OSFIE	CSWIE	—	—	—	—	—	ADIE
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **OSFIE:** Oscillator Fail Interrupt Enable bit
1 = Enables the Oscillator Fail Interrupt
0 = Disables the Oscillator Fail Interrupt

bit 6 **CSWIE:** Clock Switch Complete Interrupt Enable bit
1 = The clock switch module interrupt is enabled
0 = The clock switch module interrupt is disabled

bit 5-1 **Unimplemented:** Read as ‘0’

bit 0 **ADIE:** Analog-to-Digital Converter (ADC) Interrupt Enable bit
1 = Enables the ADC interrupt
0 = Disables the ADC interrupt

Note: Bit PEIE of the INTCON register must be set to enable any peripheral interrupt controlled by registers PIE1-PIE7

TABLE 10-1: SUMMARY OF REGISTERS ASSOCIATED WITH INTERRUPTS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
INTCON	GIE	PEIE	—	—	—	—	—	INTEDG	124
PIE0	—	—	TMR0IE	IOCIE	—	—	—	INTE	125
PIE1	OSFIE	CSWIE	—	—	—	—	—	ADIE	126
PIE2	—	ZCDIE	—	—	—	—	C2IE	C1IE	127
PIE3	RC2IE	TX2IE	RC1IE	TX1IE	—	—	BCL1IE	SSP1IE	128
PIE4	—	—	—	—	—	—	TMR2IE	TMR1IE	129
PIE5	CLC4IE	CLC3IE	CLC2IE	CLC1IE	—	—	—	TMR1GIE	130
PIE6	—	—	—	—	—	—	CCP2IE	CCP1IE	131
PIE7	—	—	NVMIE	NCO1IE	—	—	—	CWG1IE	132
PIR0	—	—	TMR0IF	IOCIF	—	—	—	INTF	133
PIR1	OSFIF	CSWIF	—	—	—	—	—	ADIF	134
PIR2	—	ZCDIF	—	—	—	—	C2IF	C1IF	135
PIR3	RC2IF	TX2IF	RC1IF	TX1IF	—	—	BCL1IF	SSP1IF	136
PIR4	—	—	—	—	—	—	TMR2IF	TMR1IF	137
PIR5	CLC4IF	CLC3IF	CLC2IF	CLC1IF	—	—	—	TMR1GIF	138
PIR6	—	—	—	—	—	—	CCP2IF	CCP1IF	139
PIR7	—	—	NVMIF	NCO1IF	—	—	—	CWG1IF	140

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by interrupts.

13.3.4 NVMREG WRITE TO PROGRAM MEMORY

Program memory is programmed using the following steps:

1. Load the address of the row to be programmed into NVMADRH:NVMADRL.
2. Load each write latch with data.
3. Initiate a programming operation.
4. Repeat steps 1 through 3 until all data is written.

Before writing to program memory, the word(s) to be written must be erased or previously unwritten. Program memory can only be erased one row at a time. No automatic erase occurs upon the initiation of the write.

Program memory can be written one or more words at a time. The maximum number of words written at one time is equal to the number of write latches. See Figure 13-4 (row writes to program memory with 32 write latches) for more details.

The write latches are aligned to the Flash row address boundary defined by the upper ten bits of NVMADRH:NVMADRL, (NVMADRH<6:0>:NVMADRL<7:5>) with the lower five bits of NVMADRL, (NVMADRL<4:0>) determining the write latch being loaded. Write operations do not cross these boundaries. At the completion of a program memory write operation, the data in the write latches is reset to contain 0x3FFF.

The following steps should be completed to load the write latches and program a row of program memory. These steps are divided into two parts. First, each write latch is loaded with data from the NVMDATH:NVMDATL using the unlock sequence with LWLO = 1. When the last word to be loaded into the write latch is ready, the LWLO bit is cleared and the unlock sequence executed. This initiates the programming operation, writing all the latches into Flash program memory.

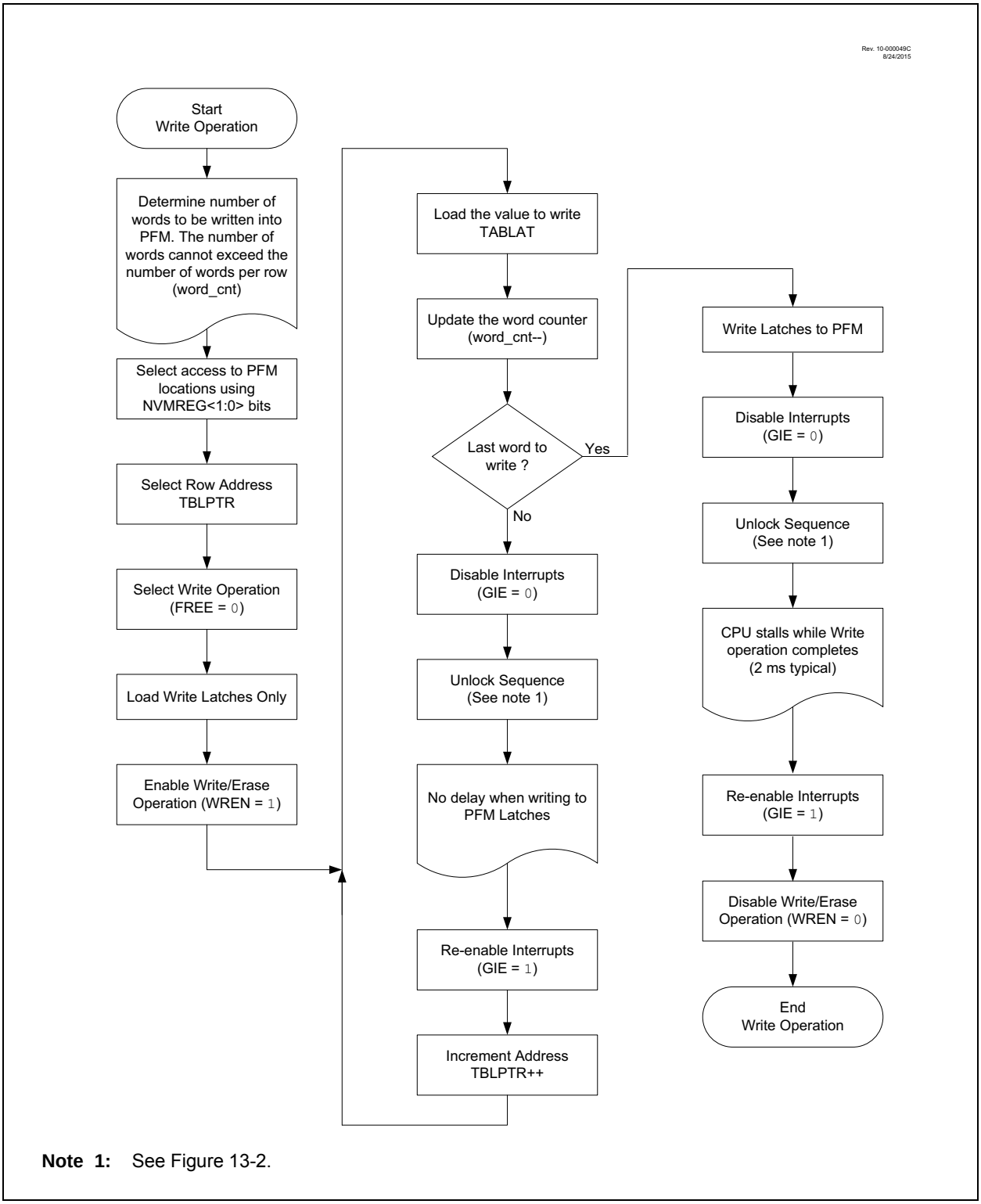
Note:	The special unlock sequence is required to load a write latch with data or initiate a Flash programming operation. If the unlock sequence is interrupted, writing to the latches or program memory will not be initiated.

1. Set the WREN bit of the NVMCON1 register.
2. Clear the NVMREGS bit of the NVMCON1 register.
3. Set the LWLO bit of the NVMCON1 register. When the LWLO bit of the NVMCON1 register is '1', the write sequence will only load the write latches and will not initiate the write to Flash program memory.
4. Load the NVMADRH:NVMADRL register pair with the address of the location to be written.
5. Load the NVMDATH:NVMDATL register pair with the program memory data to be written.
6. Execute the unlock sequence (**Section 13.3.2 "NVM Unlock Sequence"**). The write latch is now loaded.
7. Increment the NVMADRH:NVMADRL register pair to point to the next location.
8. Repeat steps 5 through 7 until all but the last write latch has been loaded.
9. Clear the LWLO bit of the NVMCON1 register. When the LWLO bit of the NVMCON1 register is '0', the write sequence will initiate the write to Flash program memory.
10. Load the NVMDATH:NVMDATL register pair with the program memory data to be written.
11. Execute the unlock sequence (**Section 13.3.2 "NVM Unlock Sequence"**). The entire program memory latch content is now written to Flash program memory.

Note:	The program memory write latches are reset to the blank state (0x3FFF) at the completion of every write or erase operation. As a result, it is not necessary to load all the program memory write latches. Unloaded latches will remain in the blank state.

An example of the complete write sequence is shown in Example 13-4. The initial address is loaded into the NVMADRH:NVMADRL register pair; the data is loaded using indirect addressing.

FIGURE 13-5: PROGRAM FLASH MEMORY WRITE FLOWCHART



Note 1: See Figure 13-2.

REGISTER 14-11: LATB: PORTB DATA LATCH REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	U-0	U-0	U-0	U-0
LATB7	LATB6	LATB5	LATB4	—	—	—	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-4 **LATB<7:4>**: RB<7:4> Output Latch Value bits(1)

bit 3-0 **Unimplemented**: Read as '0'

Note 1: Writes to PORTB are actually written to corresponding LATB register. Reads from PORTB register returns actual I/O pin values.

REGISTER 14-12: ANSELB: PORTB ANALOG SELECT REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	U-0	U-0	U-0	U-0
ANSB7	ANSB6	ANSB5	ANSB4	—	—	—	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-4 **ANSB<7:4>**: Analog Select between Analog or Digital Function on pins RB<7:4>, respectively
1 = Analog input. Pin is assigned as analog input(1). Digital input buffer disabled.
0 = Digital I/O. Pin is assigned to port or digital special function.

bit 3-0 **Unimplemented**: Read as '0'

Note 1: When setting a pin to an analog input, the corresponding TRIS bit must be set to Input mode in order to allow external control of the voltage on the pin.

REGISTER 17-4: IOCBP: INTERRUPT-ON-CHANGE PORTB POSITIVE EDGE REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	U-0	U-0	U-0
IOCBP7	IOCBP6	IOCBP5	IOCBP4	—	—	—	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-4 **IOCBP<7:4>:** Interrupt-on-Change PORTB Positive Edge Enable bits
1 = Interrupt-on-Change enabled on the pin for a positive-going edge. IOCBFx bit and IOCIF flag will be set upon detecting an edge.
0 = Interrupt-on-Change disabled for the associated pin.

bit 3-0 **Unimplemented:** read as '0'

REGISTER 17-5: IOCBN: INTERRUPT-ON-CHANGE PORTB NEGATIVE EDGE REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	U-0	U-0	U-0
IOCBN7	IOCBN6	IOCBN5	IOCBN4	—	—	—	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-4 **IOCBN<7:4>:** Interrupt-on-Change PORTB Negative Edge Enable bits
1 = Interrupt-on-Change enabled on the pin for a negative-going edge. IOCBFx bit and IOCIF flag will be set upon detecting an edge.
0 = Interrupt-on-Change disabled for the associated pin.

bit 3-0 **Unimplemented:** read as '0'

REGISTER 20-3: ADACT: A/D AUTO-CONVERSION TRIGGER

U-0	U-0	U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
—	—	—	—	ADACT<3:0>			
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-4 **Unimplemented:** Read as ‘0’

bit 3-0 **ADACT<3:0>:** Auto-Conversion Trigger Selection bits(1) (see Table 20-2)

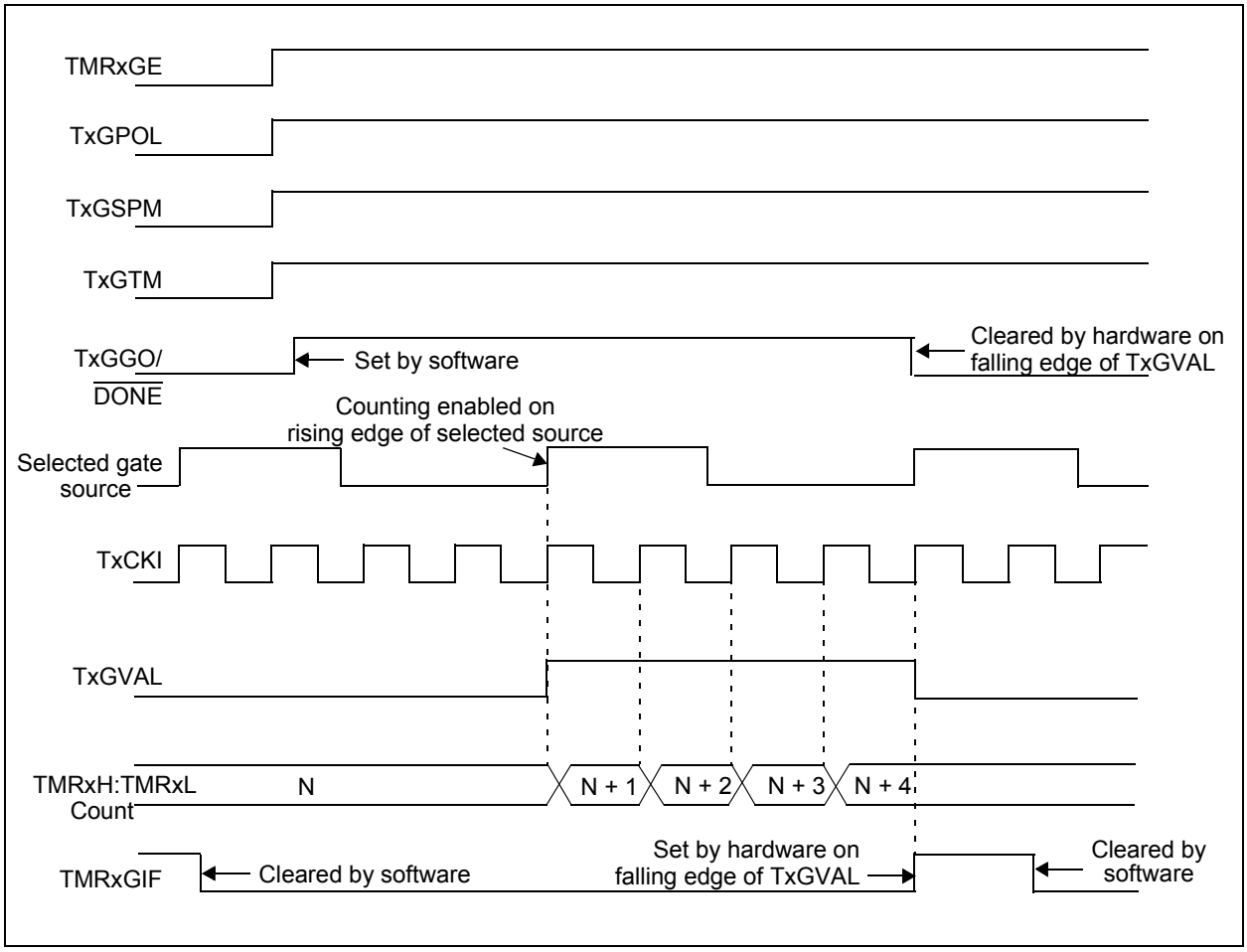
Note 1: This is a rising edge sensitive input for all sources.

TABLE 22-1: SUMMARY OF REGISTERS ASSOCIATED WITH NCO

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
INTCON	GIE	PEIE	—	—	—	—	—	INTEDG	124
PIR7	—	—	NVMIF	NCO1IF	—	—	—	CWG1IF	140
PIE7	—	—	NVMIE	NCO1IE	—	—	—	CWG1IE	132
NCO1CON	N1EN	—	N1OUT	N1POL	—	—	—	N1PFM	249
NCO1CLK	N1PWS<2:0>			—	N1CKS<3:0>				250
NCO1ACCL	NCO1ACC<7:0>								251
NCO1ACCH	NCO1ACC<15:8>								251
NCO1ACCU	—	—	—	—	NCO1ACC<19:16>				251
NCO1INCL	NCO1INC<7:0>								252
NCO1INCH	NCO1INC<15:8>								252
NCO1INCU	—	—	—	—	NCO1AINC<19:16>				252
RxyPPS	—	—	—	RxyPPS<4:0>					200

Legend: – = unimplemented read as '0'. Shaded cells are not used for NCO module.

FIGURE 26-6: TIMER1 GATE SINGLE-PULSE AND TOGGLE COMBINED MODE



29.1 Standard PWM Mode

The standard PWM mode generates a Pulse-Width Modulation (PWM) signal on the PWMx pin with up to ten bits of resolution. The period, duty cycle, and resolution are controlled by the following registers:

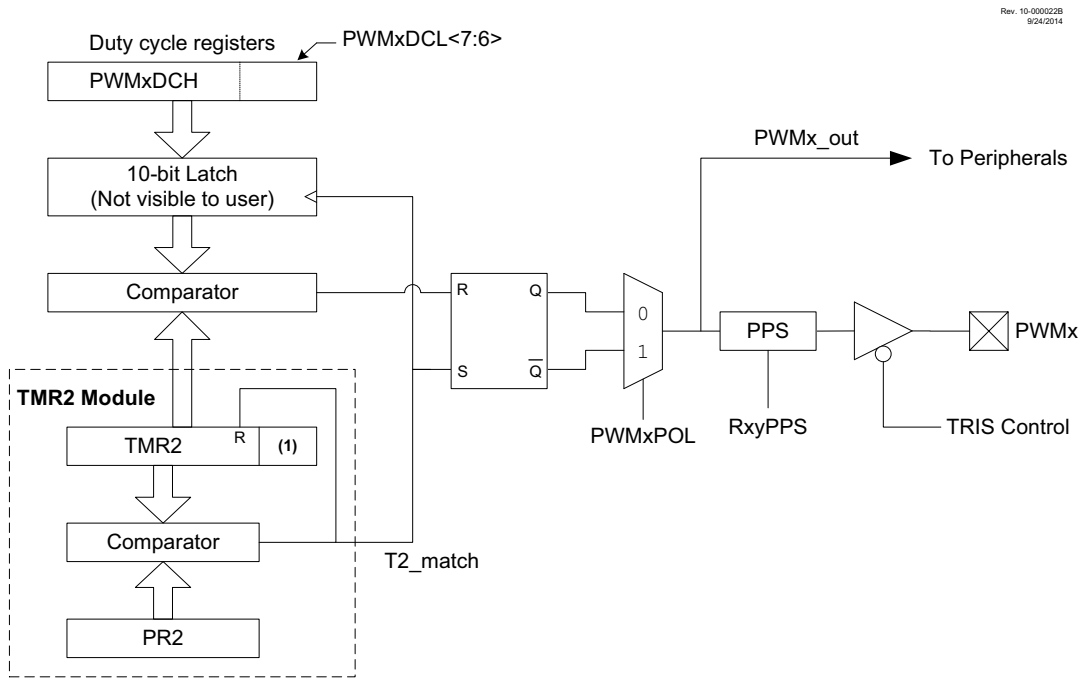
- TMR2 register
- PR2 register
- PWMxCON registers
- PWMxDCH registers
- PWMxDCL registers

Figure 29-2 shows a simplified block diagram of PWM operation.

If PWMPOL = 0, the default state of the output is '0'. If PWMPOL = 1, the default state is '1'. If PWMEN = 0, the output will be the default state.

Note:	The corresponding TRIS bit must be cleared to enable the PWM output on the PWMx pin

FIGURE 29-2: SIMPLIFIED PWM BLOCK DIAGRAM



Note 1: 8-bit timer is concatenated with two bits generated by Fosc or two bits of the internal prescaler to create 10-bit time-base.

REGISTER 31-11: CLCDATA: CLC DATA OUTPUT

U-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
—	—	—	—	MLC4OUT	MLC3OUT	MLC2OUT	MLC1OUT
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-4 **Unimplemented:** Read as ‘0’

bit 3 **MLC4OUT:** Mirror copy of LC4OUT bit

bit 2 **MLC3OUT:** Mirror copy of LC3OUT bit

bit 1 **MLC2OUT:** Mirror copy of LC2OUT bit

bit 0 **MLC1OUT:** Mirror copy of LC1OUT bit

TABLE 31-4: SUMMARY OF REGISTERS ASSOCIATED WITH CLCx (continued)

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
CLC4GLS1	—	—	LC4G2D3T	LC4G2D3N	LC4G2D2T	LC4G2D2N	LC4G2D1T	LC4G2D1N	369
CLC4GLS2	—	—	LC4G3D3T	LC4G3D3N	LC4G3D2T	LC4G3D2N	LC4G3D1T	LC4G3D1N	370
CLC4GLS3	—	—	LC4G4D3T	LC4G4D3N	LC4G4D2T	LC4G4D2N	LC4G4D1T	LC4G4D1N	371
CLCIN0PPS	—	—	CLCIN0PPS<5:0>						199
CLCIN1PPS	—	—	CLCIN1PPS<5:0>						199
CLCIN2PPS	—	—	CLCIN2PPS<5:0>						199
CLCIN3PPS	—	—	CLCIN3PPS<5:0>						199

Legend: — = unimplemented, read as '0'. Shaded cells are unused by the CLCx modules.

37.2 Standard Operating Conditions

The standard operating conditions for any device are defined as:

Operating Voltage: $V_{DDMIN} \leq V_{DD} \leq V_{DDMAX}$
Operating Temperature: $T_{A\_MIN} \leq T_A \leq T_{A\_MAX}$

V_{DD} — Operating Supply Voltage(1)

PIC16LF15325/45

- V_{DDMIN} (Fosc ≤ 16 MHz) ..... +1.8V
- V_{DDMIN} (Fosc ≤ 32 MHz) ..... +2.5V
- V_{DDMAX} ..... +3.6V

PIC16F15325/45

- V_{DDMIN} (Fosc ≤ 16 MHz) ..... +2.3V
- V_{DDMIN} (Fosc ≤ 32 MHz) ..... +2.5V
- V_{DDMAX} ..... +5.5V

T_A — Operating Ambient Temperature Range

Industrial Temperature

- T_{A_MIN} ..... -40°C
- T_{A_MAX} ..... +85°C

Extended Temperature

- T_{A_MIN} ..... -40°C
- T_{A_MAX} ..... +125°C

Note 1: See Parameter Supply Voltage, DS Characteristics: Supply Voltage.

TABLE 37-4: I/O PORTS

Standard Operating Conditions (unless otherwise stated)							
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
	V_{IL}	**Input Low Voltage**					
		I/O PORT:					
D300		with TTL buffer	—	—	0.8	V	$4.5V \le V_{DD} \le 5.5V$
D301			—	—	0.15 V_{DD}	V	$1.8V \le V_{DD} \le 4.5V$
D302		with Schmitt Trigger buffer	—	—	0.2 V_{DD}	V	$2.0V \le V_{DD} \le 5.5V$
D303		with I^2C levels	—	—	0.3 V_{DD}	V	
D304		with SMBus levels	—	—	0.8	V	$2.7V \le V_{DD} \le 5.5V$
D305		$\overline{MCLR}$	—	—	0.2 V_{DD}	V	
	V_{IH}	**Input High Voltage**					
		I/O PORT:					
D320		with TTL buffer	2.0	—	—	V	$4.5V \le V_{DD} \le 5.5V$
D321			0.25 V_{DD} + 0.8	—	—	V	$1.8V \le V_{DD} \le 4.5V$
D322		with Schmitt Trigger buffer	0.8 V_{DD}	—	—	V	$2.0V \le V_{DD} \le 5.5V$
D323		with I^2C levels	0.7 V_{DD}	—	—	V	
D324		with SMBus levels	2.1	—	—	V	$2.7V \le V_{DD} \le 5.5V$
D325		$\overline{MCLR}$	0.7 V_{DD}	—	—	V	
	I_{IL}	**Input Leakage Current(1)**					
D340		I/O Ports	—	± 5	± 125	nA	$V_{SS} \le V_{PIN} \le V_{DD}$, Pin at high-impedance, 85°C
D341			—	± 5	± 1000	nA	$V_{SS} \le V_{PIN} \le V_{DD}$, Pin at high-impedance, 125°C
D342		$\overline{MCLR}$(2)	—	± 50	± 200	nA	$V_{SS} \le V_{PIN} \le V_{DD}$, Pin at high-impedance, 85°C
	I_{PUR}	**Weak Pull-up Current**					
D350			25	120	200	µA	V_{DD} = 3.0V, V_{PIN} = V_{SS}
	V_{OL}	**Output Low Voltage**					
D360		I/O ports	—	—	0.6	V	I_{OL} = 10.0mA, V_{DD} = 3.0V
	V_{OH}	**Output High Voltage**					
D370		I/O ports	V_{DD} - 0.7	—	—	V	I_{OH} = 6.0 mA, V_{DD} = 3.0V
D380	C_{IO}	**All I/O pins**	—	5	50	pF	

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Negative current is defined as current sourced by the pin.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

TABLE 37-6: THERMAL CHARACTERISTICS

Standard Operating Conditions (unless otherwise stated)					
Param. No.	**Sym.**	**Characteristic**	**Typ.**	**Units**	**Conditions**
TH01	θJA	Thermal Resistance Junction to Ambient	70	°C/W	14-pin SPDIP package
			95.3C	°C/W	14-pin SOIC package
			100.0	°C/W	14-pin TSSOP package
			51.5	°C/W	16-pin UQFN 4x4mm package
			62.2	°C/W	20-pin PDIP package
			87.3	°C/W	20-pin SSOP package
			77.7	°C/W	20-pin SOIC package
			43.0	°C/W	20-pin UQFN 4x4mm package
TH02	θJC	Thermal Resistance Junction to Case	32.75	°C/W	14-pin PDIP package
			31.0	°C/W	14-pin SOIC package
			24.4	°C/W	14-pin TSSOP package
			5.4	°C/W	16-pin UQFN 4x4mm package
			27.5	°C/W	20-pin PDIP package
			31.1	°C/W	20-pin SSOP package
			23.1	°C/W	20-pin SOIC package
			5.3	°C/W	20-pin UQFN 4x4mm package
TH03	TJMAX	Maximum Junction Temperature	150	°C	
TH04	PD	Power Dissipation	—	W	PD = PINTERNAL + PI/O
TH05	PINTERNAL	Internal Power Dissipation	—	W	PINTERNAL = IDD x VDD(1)
TH06	PI/O	I/O Power Dissipation	—	W	PI/O = Σ (IOL * VOL) + Σ (IOH * (VDD - VOH))
TH07	PDER	Derated Power	—	W	PDER = PDMAX (TJ - TA)/θJA(2)

Note 1: IDD is current to run the chip alone without driving any load on the output pins.
2: TA = Ambient Temperature, TJ = Junction Temperature

FIGURE 37-7: CLKOUT AND I/O TIMING

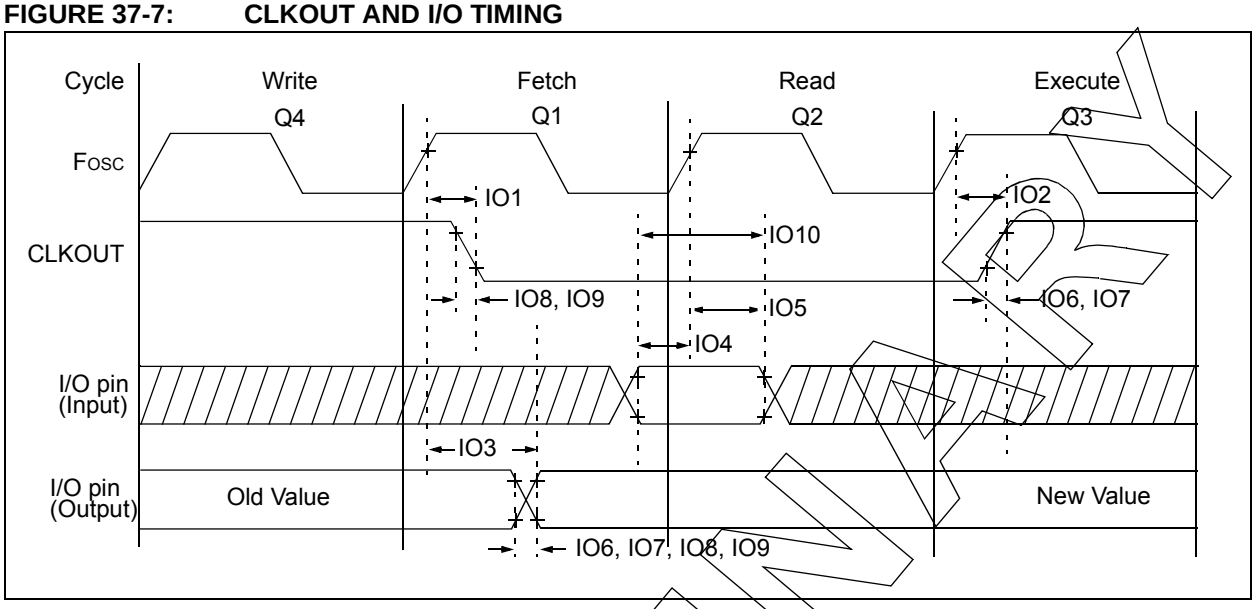


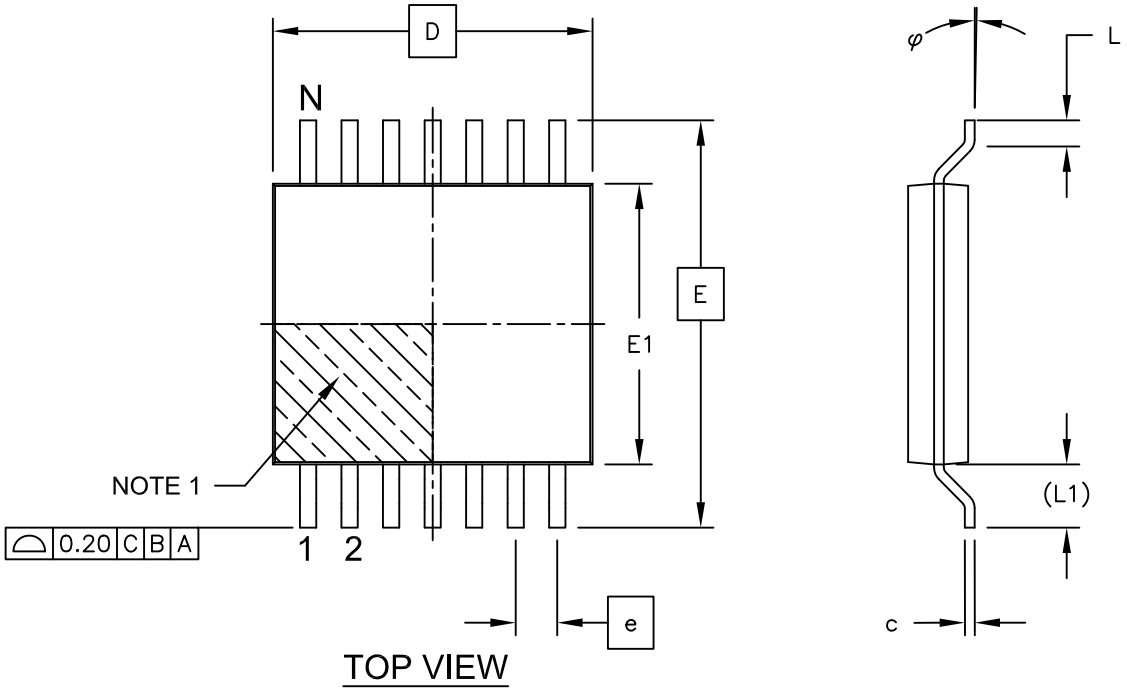
TABLE 37-10: I/O AND CLKOUT TIMING SPECIFICATIONS

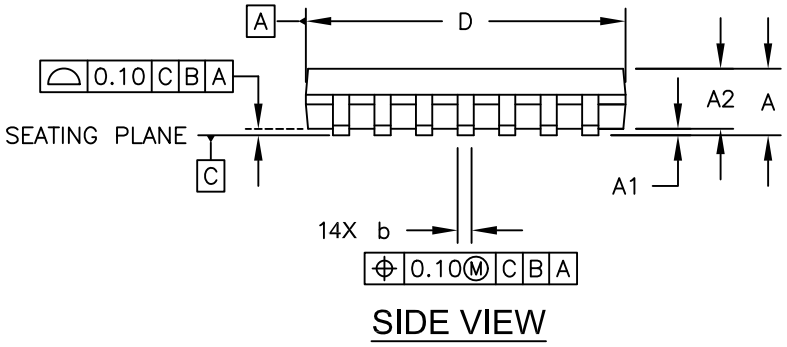
Standard Operating Conditions (unless otherwise stated)							
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
IO1*	$T_{CLKOUTH}$	CLKOUT rising edge delay (rising edge Fosc (Q1 cycle) to falling edge CLKOUT	—	—	70	ns	
IO2*	$T_{CLKOUTL}$	CLKOUT falling edge delay (rising edge Fosc (Q3 cycle) to rising edge CLKOUT	—	—	72	ns	
IO3*	T_{IO_VALID}	Port output valid time (rising edge Fosc (Q1 cycle) to port valid)	—	50	70	ns	
IO4*	T_{IO_SETUP}	Port input setup time (Setup time before rising edge Fosc – Q2 cycle)	20	—	—	ns	
IO5*	T_{IO_HOLD}	Port input hold time (Hold time after rising edge Fosc – Q2 cycle)	50	—	—	ns	
IO6*	T_{IOR_SLREN}	Port I/O rise time, slew rate enabled	—	25	—	ns	V_{DD} = 3.0V
IO7*	T_{IOR_SLRDIS}	Port I/O rise time, slew rate disabled	—	5	—	ns	V_{DD} = 3.0V
IO8*	T_{IOF_SLREN}	Port I/O fall time, slew rate enabled	—	25	—	ns	V_{DD} = 3.0V
IO9*	T_{IOF_SLRDIS}	Port I/O fall time, slew rate disabled	—	5	—	ns	V_{DD} = 3.0V
IO10*	T_{INT}	INT pin high or low time to trigger an interrupt	25	—	—	ns	
IO11*	T_{IOC}	Interrupt-on-Change minimum high or low time to trigger interrupt	25	—	—	ns	

*These parameters are characterized but not tested.

14-Lead Plastic Thin Shrink Small Outline (ST) - 4.4 mm Body [TSSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





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